



General Description

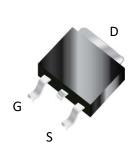
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

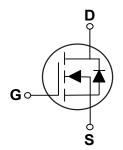
BV _{DSS}	R _{DS(ON)}	I_D
30 V	5 mΩ	80 A

Features

- $\cdot R_{DS(ON)} \le 5m\Omega@V_{GS} = 10V$
- · Improved dv/dt capability
- Fast switching

TO-252 Pin Configuration





Applications

- · NB / VGA / V_{CORE}
- POL Applications
- · SMPS 2nd SR

Absolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units			
V _{DS}	Drain-Source Voltage	30	V			
V_{GS}	Gate-Source Voltage	±20	V			
1	Drain Current - Continuous (T _C =25°C)	80	Α			
I _D	Drain Current - Continuous (T _C =100°C)	51				
I _{DM}	Drain Current - Pulsed (NOTE 1)	320	Α			
EAS	Single Pulse Avalanche Energy (NOTE 2)	88	mJ			
IAS	Single Pulse Avalanche Current (NOTE 2)	42	Α			
P_{D}	Power Dissipation (T _C =25°C)	54	W			
ΓD	Power Dissipation – Derate above 25°C	0.43	W/°C			
T _J	Operating Junction Temperature Range	-55 to 150	°C			
T _{STG}	Storage Temperature Range	-55 to 150	°C			
Marking Code		NC5P0				

Thermal Characteristics					
Symbol	Symbol Parameter		Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		62	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction to Case		2.3	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Syn	lodn	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV	DSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
I _{DSS} Drain-Source Leakage Current	Drain Source Leakage Current	V_{DS} =30V , V_{GS} =0V , T_J =25°C	-		1	uA	
	Diam-Source Leakage Guirent	V_{DS} =24V , V_{GS} =0V , T_J =125°C	-		10	uA	
I_{G}	iss	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V	-		±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I Reader	Static Drain-Source On-Resistance	V_{GS} =10V , I_D =30A		3.7	5	mΩ
	(NOTE 3)	V _{GS} =4.5V , I _D =25A		6	9	11177
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0	1.6	2.5	V
gfs	Forward Transconductance	V _{GS} =10V , I _D =10A		18		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =20A		11.1		
Q_gs	Gate-Source Charge	$V_{DS} = 15V$, $V_{GS} = 4.5V$, $I_{D} = 20A$ (NOTE 3 \ 4)		1.85		nC
Q_{gd}	Gate-Drain Charge	(14012 3 + 4)		6.8		
$T_{d(on)}$	Turn-On Delay Time			7.5		
T_r	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω ,		14.5		nS
$T_{d(off)}$	Turn-Off Delay Time	I _D =15A (NOTE 3 · 4)		35.2		113
T_f	Fall Time			9.6		
C _{iss}	Input Capacitance			1160		
C_{oss}	Output Capacitance	V_{DS} =25V , V_{GS} =0V , f=1MHz		200		pF
C_{rss}	Reverse Transfer Capacitance			180		
R_g	Gate Resistance	V_{GS} =0V , V_{DS} =0V , f=1MHz		2.5		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V,Force Current			80	Α
I _{SM}	Pulsed Source Current				320	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =42A, R_{G} =25 Ω , Starting T_{J} =25 $^{\circ}$ C.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.





Characteristics Curves

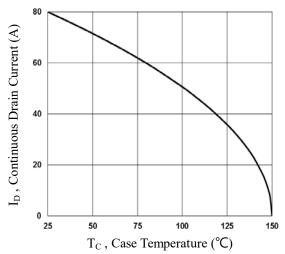


Fig.1 Continuous Drain Current vs. T_c

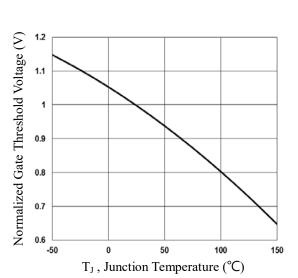


Fig.3 Normalized V_{th} vs. T_J

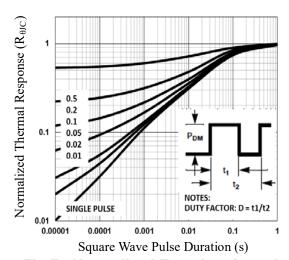


Fig.5 Normalized Transient Impedance

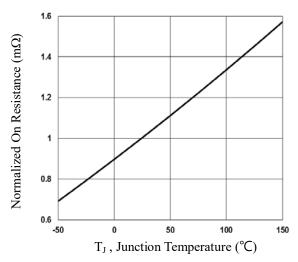


Fig.2 Normalized RDSON vs. T_J

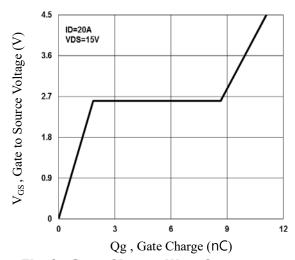


Fig.4 Gate Charge Waveform

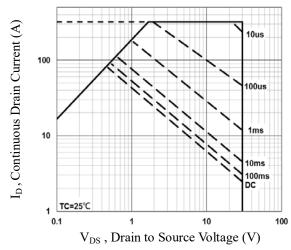


Fig.6 Maximum Safe Opration Areae





Characteristics Curves

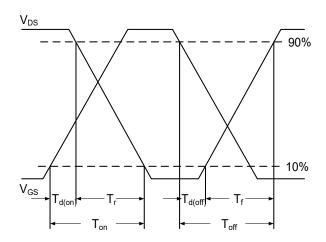
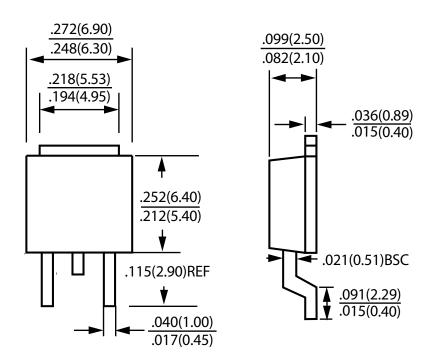


Fig.7 Switching Time Waveform

Package Outline Dimensions



TO-252Dimensions in inches and (millimeters)





LEGAL DISCLAIMER

- The product is provided "AS IS" without any guarantees or warranty. In association with the product, Eris Technology Corporation, its affiliates, and their directors, officers, employees, agents, successors and assigns (collectively, the "Eris") makes no warranties of any kind, either express or implied, including but not limited to warranties of merchantability, fitness for a particular purpose, of title, or of non-infringement of third party rights.
- The information in this document and any product described herein are subject to change without notice and should not be construed as a commitment by Eris. Eris assumes no responsibility for any errors that may appear in this document.
- Eris does not assume any liability arising out of the application or use of this document or any product described herein, any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Eris and all the companies whose products are represented on Eris website, harmless against all damages.
- No license, express or implied, by estoppels or otherwise, to any intellectual property is granted by this document or by any conduct of Eris. Product name and markings notes herein may be trademarks of their respective owners.
- Eris does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- Should Customers purchase or use Eris products for any unintended or unauthorized application, Customers shall indemnify and hold Eris and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.
- The official text is written in English and the English version of this document is the only version endorsed by Eris. Any discrepancies or differences created in the translations are not binding and have no legal effect on Eris for compliance or enforcement purposes.